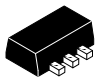
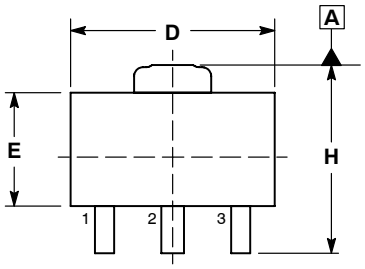


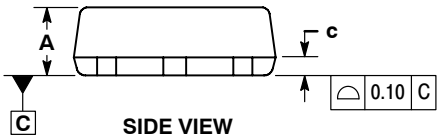
SCALE 2:1

SOT−89, 3 LEAD
CASE 528AG
ISSUE O

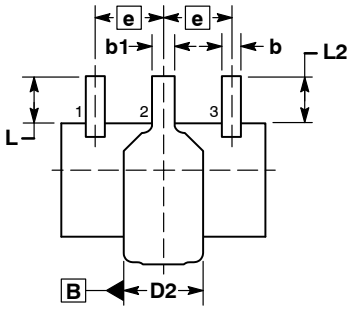
DATE 04 MAR 2014



TOP VIEW



SIDE VIEW

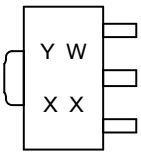


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS INCLUDES LEAD FINISH.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. DIMENSIONS L, L2, D2, AND H ARE MEASURED AT DATUM PLANE C.
6. CENTER LEAD CONTOUR MAY VARY WITHIN THE REGION DEFINED BY DIMENSION E.
7. DIMENSION D2 IS DEFINED AT ITS WIDEST POINT.

	MILLIMETERS	
DIM	MIN	MAX
A	1.40	1.60
b	0.38	0.47
b1	0.46	0.55
c	0.40	0.44
D	4.40	4.60
D2	1.60	1.90
E	2.40	2.60
e	1.50 BSC	
H	4.05	4.25
L	0.89	1.20

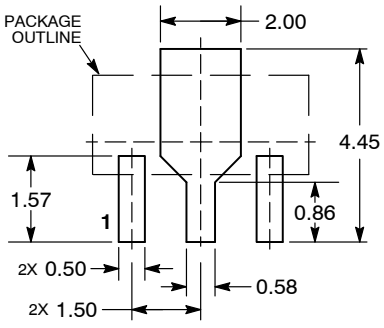
GENERIC MARKING DIAGRAM*



Y = Year
W = Work Week
XX = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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